



**Statement of Materials, Construction**

<b>LEAD-FREE -- 48L QFN -- TABLE OF MATERIAL DECLARATION</b>								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Copper Alloy (with silver plating)	0.04128	Cu	7440-50-8	0.04008	72.23	97.10
				Fe	7439-89-6	0.00103	1.86	2.50
				P	7723-14-0	0.00004	0.07	0.10
				Zn	7440-66-6	0.00008	0.15	0.20
				Silver Plating	7440-22-4	0.00004	0.07	0.10
2	Die	Silicon Chip	0.00558	Si	7440-21-3	0.00558	10.05	99.99
3	Die Attach Material	Conductive Epoxy	0.00075	Silver (Ag)	7440-22-4	0.00055	0.99	73.50
				Epoxy Resin A	9003-36-5	0.00007	0.13	10.00
				Epoxy Resin B	5026-74-4	0.00004	0.07	5.00
				Hardener A	Proprietary	0.00005	0.09	7.00
				Hardener B	Proprietary	0.00002	0.04	3.00
				Elastomer	Proprietary	0.00001	0.02	1.50
4	Wire	Gold	0.00053	Au	7440-57-5	0.00053	0.95	99.99
5	Lead Finish	Tin	0.00232	Sn	7440-31-5	0.00232	4.18	100
6	Encapsulation	Epoxy Resin	0.00504	Fused Silica	60676-86-0	0.00472	8.51	93.70
				Epoxy Resin	Proprietary	0.00015	0.27	3.00
				Phenol Resin	Proprietary	0.00015	0.27	3.00
				Carbon Black	1333-86-4	0.00002	0.03	0.30
Total Package Weight =			0.05549					

**Note:** Component Weight based on assembly of generic parts.

**Conclusion:**

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%